BGA Reballing Machine with 0.4-0.8Mpa Air Source and 2000W Total Power for 0.2-1.27mm Solder Balls, BGA Rework Station for PCB Repair

Our Product Introduction

Basic Information

- Brand Name: WISDOMSHOW
- Certification: CE
- Model Number: DS-300
- Minimum Order Quantity: 1pcs
- Packaging Details: wood carton
- Delivery Time: 5-8 working days
- Supply Ability: 200Sets / Month



Product Specification

- Solder Ball Size Range: 0.2-1.27mm
- Total Power: 2000W
- Power Supply: AC220V 50Hz
- Air Source: 0.4-0.8Mpa
- Applicable Chip Size: 13×3-120×120mm
- Placement Accuracy: 0.02mm
- Highlight: **0.4-0.8Mpa Air Source BGA Reballing Machine**, **0.2-1.27mm Solder Ball BGA Rework Station**, **2000W Total Power BGA Reballing Machine**

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Product Description

Product Description:

The BGA Reballing Machine is a state-of-the-art Ball Grid Array Rework Station designed for precision and efficiency in soldering ball grid arrays. This advanced BGA Soldering Repair Machine is engineered to meet the rigorous demands of modern electronics manufacturing and repair, providing outstanding performance and reliability.

One of the standout features of this Ball Grid Array Rework Station is its ability to handle a wide solder ball size range, from as small as 0.2mm to as large as 1.27mm. This versatility makes it suitable for a variety of BGA components, accommodating different package sizes and types with ease. Whether you are working on fine-pitch BGAs or larger packages, this machine ensures consistent and accurate ball placement every time.

Powered by an efficient AC220V 50Hz power supply, the BGA Reballing Machine offers a stable and reliable energy source to support continuous operation. Its total power consumption of 2000W ensures that the machine has ample power to perform precise heating and reballing tasks without interruption or performance degradation. This powerful setup allows for fast heating cycles and quick turnaround times, improving overall productivity in the rework process.

Precision is critical in BGA reballing, and this Ball Grid Array Rework Station excels in this area with an impressive placement accuracy of 0.02mm. Such high precision ensures that solder balls are positioned accurately on the pads, minimizing the risk of defects during soldering and enhancing the quality of the final assembly. This level of accuracy is essential for maintaining the integrity of complex circuits and avoiding costly rework or failures down the line.

The machine operates with an air source pressure range of 0.4-0.8Mpa, providing the necessary pneumatic control for various stages of the reballing process, including ball placement and reflow operations. This air pressure range is optimized to deliver stable and controlled airflow, contributing to the overall precision and reliability of the BGA Soldering Repair Machine.

Designed with user convenience and operational efficiency in mind, the BGA Reballing Machine features an intuitive interface and robust construction. This Ball Grid Array Rework Station is suitable for both small-scale repair shops and large-scale manufacturing facilities, offering flexibility and scalability for different production needs. Its compact design also saves valuable workspace, making it easy to integrate into existing production lines.

In summary, the BGA Reballing Machine is an indispensable tool for professionals involved in BGA soldering and repair. With its broad solder ball size compatibility, precise ball placement accuracy, powerful and stable power supply, and optimized air source pressure, it delivers exceptional performance for a wide range of applications. Whether you are performing repairs, prototyping, or full-scale production, this Ball Grid Array Rework Station ensures high-quality results and increased efficiency. Investing in this BGA Soldering Repair Machine means equipping your workspace with a reliable and precise solution tailored for the demands of modern electronics assembly and repair.

Features:

Product Name: BGA Reballing Machine

Air Source: 0.4-0.8Mpa

Power Supply: AC220V 50Hz

Placement Accuracy: 0.02mm

Solder Ball Size Range: 0.2-1.27mm

Applicable Chip Size: 13*3-120*120mm

High precision Ball Grid Array Rework Station for efficient chip reballing

Advanced BGA Soldering Repair Machine designed for reliable and accurate soldering

Comprehensive BGA Chip Reballing System suitable for various chip sizes and solder ball ranges

Technical Parameters:

Applicable Chip Size	13*3-120*120mm
Solder Ball Size Range	0.2-1.27mm
Total Power	2000W
Power Supply	AC220V 50Hz
Placement Accuracy	0.02mm
Air Source	0.4-0.8Mpa

Applications:

The WISDOMSHOW DS-300 Ball Grid Array Rework Station is an advanced BGA Soldering Repair Machine designed for precision and efficiency in electronic component maintenance and manufacturing. Originating from Shenzhen, China, this state-of-the-art BGA Chip Reballing System offers exceptional placement accuracy of 0.02mm, ensuring flawless alignment of solder balls during the reballing process. With a total power consumption of 2000W and operating on a power supply of AC220V 50Hz, the DS-300 is engineered for consistent and reliable performance in demanding environments.

This BGA Reballing Machine is ideal for use in various professional scenarios, including electronics manufacturing plants, repair centers, and research and development laboratories. It excels in applications requiring the refurbishment and reconditioning of Ball Grid Array components, enabling technicians to remove old solder balls and precisely place new ones within a size range of 0.2 to 1.27mm. The machine's air source requirement of 0.4-0.8Mpa supports stable and efficient solder ball placement, making it suitable for high-volume production lines as well as intricate prototype developments.

In repair workshops, the WISDOMSHOW DS-300 significantly improves turnaround time and quality when dealing with faulty or damaged

BGA chips, offering a cost-effective solution for extending the lifespan of electronic devices. Its high placement accuracy minimizes the risk of soldering defects, which is critical in maintaining the integrity of sophisticated circuit boards. Furthermore, the BGA Chip Reballing System is applicable in educational institutions for training purposes, providing students and engineers with hands-on experience in advanced soldering repair techniques.

Overall, the DS-300 Ball Grid Array Rework Station stands out as a versatile and indispensable tool for professionals involved in electronic manufacturing and repair. Whether used in high-precision industrial environments or specialized repair scenarios, this BGA Soldering Repair Machine delivers unmatched accuracy, efficiency, and reliability, making it a preferred choice for those seeking to achieve superior results in BGA component reballing and refurbishment.

Shenzhen Wisdomshow Technology Co.,ltd

+86 18926538696 elysia.li@wdsbga.cn bgaxraymachine.com

No. 3 Kangtai 3rd Road, Shatou Community, Shajing Street, Bao'an District, Shenzhen, China